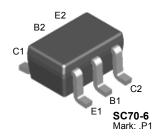


FFB5551

Dual-Chip NPN General Purpose Amplifier

- This device is deisgned for general purpose high voltage amplifiers.
- E1 is Pin 1.



Absolute Maximum Ratings* T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	160	V
V _{CBO}	Collector-Base Voltage	180	V
V _{EBO}	Emitter-Base Voltage	6.0	V
I _C	Collector Current - Continuous	200	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

Electrical Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characte	eristics	•	•		
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage *	I _C = 1.0mA, I _B = 0	160		V
V _{(BR)CBO}	Collector-Base BreakdownVoltage	$I_C = 100 \mu A, I_E = 0$	180		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	6.0		V
I _{CBO}	Collector Cut-off Current	V _{CB} = 120V, I _E = 0 V _{CB} = 120V, I _E = 0, T _A = 100°C		50 50	nA μA
I _{EBO}	Emitter Cut-off Current	V _{EB} = 4.0V, I _C = 0		50	nA
On Characte	eristics *	•	•		
h _{FE}	DC Current Gain	$V_{CE} = 5.0V, I_{C} = 1.0mA$ $V_{CE} = 5.0V, I_{C} = 10mA$ $V_{CE} = 5.0V, I_{C} = 50mA$	80 80 30	250	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C = 10mA, I _B = 1.0mA I _C = 50mA, I _B = 5.0mA		0.15 0.20	V
V _{BE} (sat)	Base-Emitter Saturation Voltage	I _C = 10mA, I _B = 1.0mA I _C = 50mA, I _B = 5.0mA		1.0 1.0	V
Small Signa	I Characteristics	·			
f _T	Current gain Bandwidth Product	V _{CE} = 10V, I _C = 10mA f = 100MHz	100	300	MHz
C _{obo}	Output Capacitance	V _{CB} = 10V, I _E = 0, f = 1.0MHz		6.0	pF

* Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2.0\%$

Thermal Characteristics T _A =25°C unless otherwise noted			
Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	200	mW
	Derate above 25°C	1.6	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	625	°C/W

Typical Characteristics

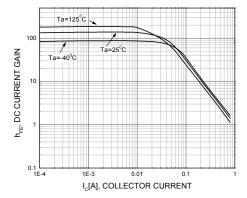


Figure 1. DC Current Gain

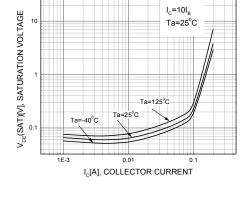


Figure 2. Collector-Emitter Saturation Voltage

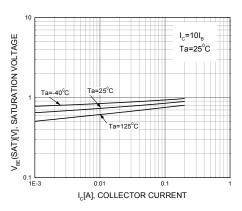


Figure 3. Base-Emitter Saturation Voltage

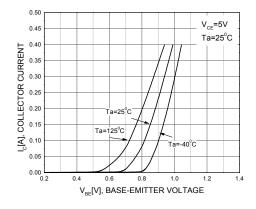
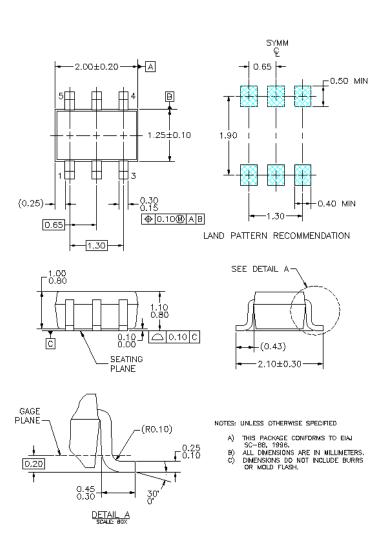


Figure 4. Base-Emitter On Voltage

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Package Dimensions

SC70-6



Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench [®]	SuperSOT™-6
$CROSSVOLT^{\text{TM}}$	FRFET™	MicroPak™	QFET™	SuperSOT™-8
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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic [®]
E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I ² C™	OCX™	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET [®]
The Power Franchise™		OPTOLOGIC [®]	SILENT SWITCHER®	VCX™
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Rev. I2

PRODUCT STATUS DEFINITIONS

Definition of Terms

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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